



Docket No.: 312302US40PCT



COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

ATTORNEYS AT LAW

RE: Application Serial No.: 10/049,270  
Applicants: Hui ZHONG, et al.  
Filing Date: June 27, 2002  
For: MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST  
COMPOSITION, METHOD FOR MANUFACTURING  
MULTILAYER PRINTED WIRING BOARD, AND  
SEMICONDUCTOR DEVICE  
Group Art Unit: 2841  
Examiner: Tuan T. DINH

SIR:

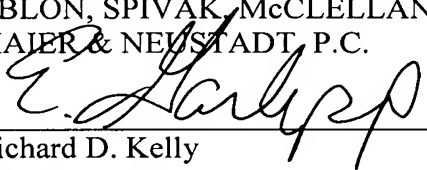
Attached hereto for filing are the following papers:

**Request for Reconsideration**

Credit card payment is being made online (if electronically filed), or is attached hereto (if paper filed), in the amount of **\$0.00** to cover any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. **15-0030**. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time.

Respectfully submitted,

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